



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kie Y. Ahn et al.

Title: METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS

Docket No.: 303.648US1

Filed: January 18, 2000

Examiner:

Serial No.: 09/484,303

Due Date: July 18, 2000

Group Art Unit: 2825

Commissioner for Patents  
Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Information Disclosure Statement (1 pgs.), Form 1449 (9 pgs.), and copies of 125 cited references.
- ☒ A Communication Concerning Co-Pending Applications (2 pgs.).

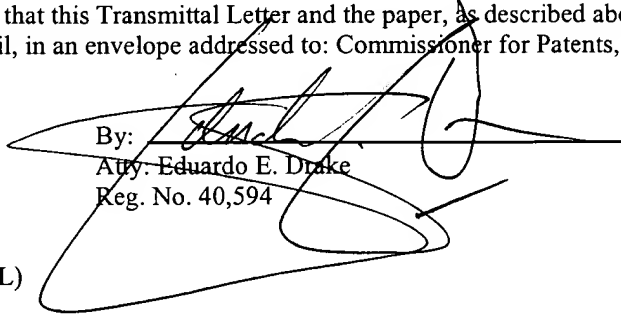
Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this Transmittal Letter and the paper, as described above, are being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 10<sup>th</sup> day of July, 2000.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

Customer Number **21186**

(GENERAL)

By:   
Atty: Eduardo E. Drake  
Reg. No. 40,594

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**INFORMATION DISCLOSURE STATEMENT**Commissioner for Patents  
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants further request that a copy of the 1449 form, initialed by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Under 37 C.F.R. §1.97(b)(3), it is believed that no fee or certificate is required with this Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 349-9593

Date

10/17/2000

By

Eduardo E. Drake  
Reg. No. 40,594

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner of Patents, Washington, D.C. 20231 on July 10, 2000.

Name

Signature

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S/N 09/484,303

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Examiner:

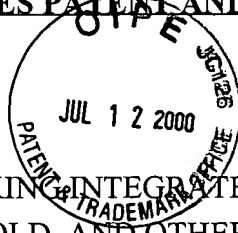
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COPPER, SILVER, GOLD, AND OTHER METALS



**COMMUNICATION CONCERNING CO-PENDING APPLICATION(S)**

Commissioner for Patents  
Washington, D.C. 20231

Applicant would like to bring to the Examiner's attention the following related co-pending application(s) in the above-identified patent application:

Serial No.	Filing Date	Attorney Docket	Title
09/483,881	01/18/2000	00303.672US1	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION
09/483,869	01/18/2000	00303.664US1	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/488,098	01/18/2000	00303.618US1	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/484,002	01/18/2000	00303.673US1	PROCESS FOR PROVIDING SEED LAYERS FOR USING ALUMINUM, COPPER, GOLD AND SILVER METALLURGY
09/032,197	02/27/1998	00303.459US1	METHODS FOR MAKING COPPER AND OTHER METAL INTERCONNECTIONS IN INTEGRATED CIRCUITS
09/128,859	08/04/1998	00303.473US1	COPPER METALLURGY IN INTEGRATED CIRCUITS
09/145,012	09/01/1998	00303.505US1	INTEGRATED-CIRCUIT WITH OXIDATION-RESISTANT POLYMERIC LAYER

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COMMUNICATION CONCERNING CO-PENDING APPLICATIONS

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Dkt: 303.648US1

09/256,123    02/24/1999    00303.505US2    FORMING SUBMICRON  
INTEGRATED-CIRCUIT WIRING FROM  
GOLD, SILVER, COPPER AND OTHER  
METALS

09/256,124    02/24/1999    00303.505US3    FORMING SUBMICRON  
INTEGRATED-CIRCUIT WIRING FROM  
GOLD, SILVER, COPPER AND OTHER  
METALS

09/584,157    05/31/2000    00303.685US1    MULTILEVEL COPPER  
INTERCONNECT WITH DOUBLE  
PASSIVATION



Respectfully submitted,

KIE Y. AHN ET AL.

By Applicant's Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 349-9593

Date

*7/12/2000*

By

*[Signature]*  
Eduardo E. Drake  
Reg. No. 40,594

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner of Patents, Washington, D.C. 20231 on July *12* 2000.

Name

*[Signature]*  
Signature

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